Kleber Applicant #202067

SKILLS

- Microscope Soldering (Trinocular)
- BGA Rework, Reballing, IC Replacement
- SMD Components: 01005, 0201, QFN, QFP
- Board Level Troubleshooting, Short Detection, Water Damage Repair
- IPC-A-610 Workmanship Standards
- PCB Assembly and Rework
- Metal Structural Assembly, Blueprint Reading
- Tools: JBC, Sugon, Quick, Hot Air Station, IR Station, Multimeter, DC Power Supply

Summary

Mico Soldering Technician with 15+ years od board-level repair expierience plus US manufacturing experienence. Expert in BGA rework and rebailling,microsoldering under trinocular microscope, and diagnostics of complex PCB faults. Proficient with JBC, Sugon, Quick station. Known for precision, steady hands and high quality rework.

Work Experience

Electronics Repair Technician/Micro Soldering-Specialist-Independant/Cellphone Repair
15 years

- Repair 1000+ cellphones and electric boards at component level
- Performed BGA reqork, CPU/IC replacement, and microsoldering under microscope
- Diagnosed short circuits, no power, no signal using schematics and boardview

Assembler - American Panel

- Perform water/fire damage mitigation, demolition and restoration
- Work in fast paced enviroment, team collaboration